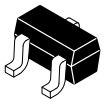
Silicon Switching Diode

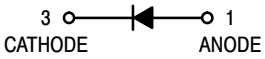
BAS16WT1G



SC−70
CASE 419
STYLE 2

Features

- S and NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q101 Qualified and PPAP Capable
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant



MAXIMUM RATINGS (T_A = 25°C)

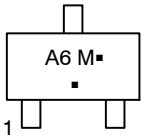
Rating	Symbol	Value	Unit
Continuous Reverse Voltage	V_R	100	V
Recurrent Peak Forward Current	I_R	200	mA
Peak Forward Surge Current Pulse Width = 10 μs	$I_{FM(surge)}$	500	mA
Total Power Dissipation, One Diode Loaded T_A = 25°C Derate above 25°C Mounted on a Ceramic Substrate (10 x 8 x 0.6 mm)	P_D	200 1.6	mW mW/°C
Operating and Storage Junction Temperature Range	T_J, T_{stg}	−55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction−to−Ambient One Diode Loaded Mounted on a Ceramic Substrate (10 x 8 x 0.6 mm)	$R_{\theta JA}$	625	°C/W

MARKING DIAGRAM



A6 = Specific Device Code
M = Date Code
▪ = Pb−Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
BAS16WT1G	SC−70 (Pb−Free)	3000 / Tape & Reel
SBAS16WT1G	SC−70 (Pb−Free)	3000 / Tape & Reel
NSVBAS16WT3G	SC−70 (Pb−Free)	10000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
Forward Voltage	V_F			mV
(I_F = 1.0 mA)		–	715	
(I_F = 10 mA)		–	866	
(I_F = 50 mA)		–	1000	
(I_F = 150 mA)		–	1250	
Reverse Current	I_R			μA
(V_R = 100 V)		–	1.0	
(V_R = 75 V, T_J = 150°C)		–	50	
(V_R = 25 V, T_J = 150°C)		–	30	
Capacitance (V_R = 0, f = 1.0 MHz)	C_D	–	2.0	pF
Reverse Recovery Time (I_F = I_R = 10 mA, R_L = 50 Ω) (Figure 1)	t_{rr}	–	6.0	ns
Stored Charge (I_F = 10 mA to V_R = 6.0 V, R_L = 500 Ω) (Figure 2)	QS	–	45	PC
Forward Recovery Voltage (I_F = 10 mA, t_r = 20 ns) (Figure 3)	V_{FR}	–	1.75	V

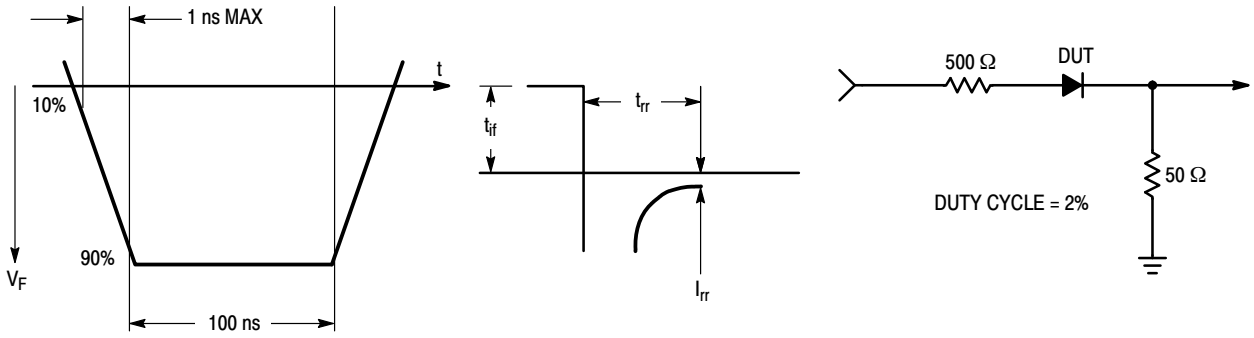


Figure 1. Reverse Recovery Time Equivalent Test Circuit

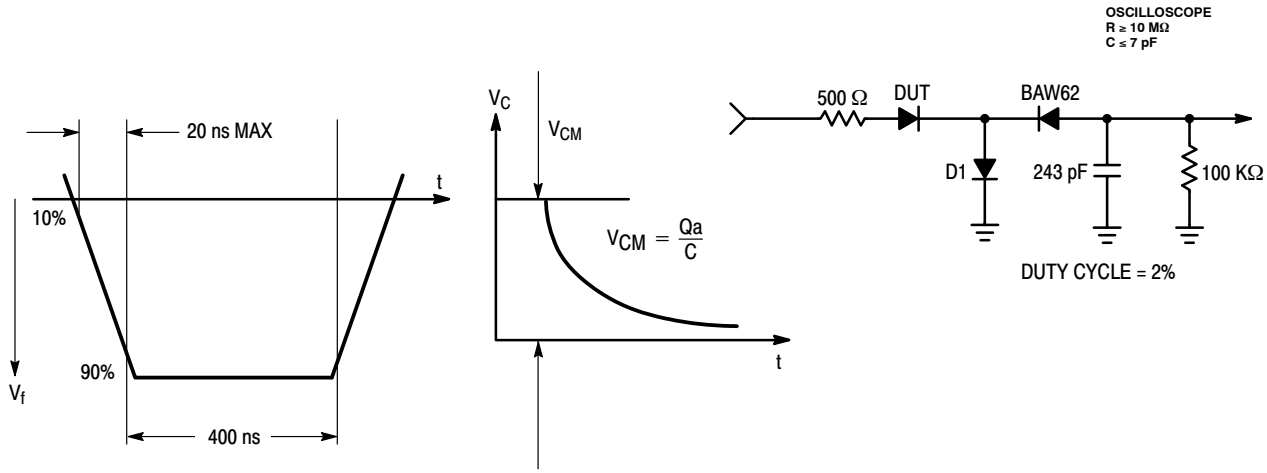


Figure 2. Stored Charge Equivalent Test Circuit

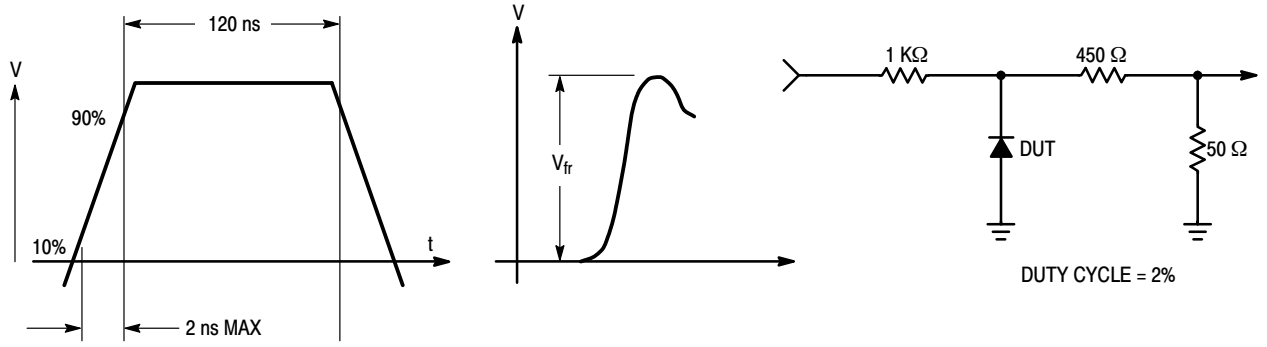


Figure 3. Forward Recovery Voltage Equivalent Test Circuit

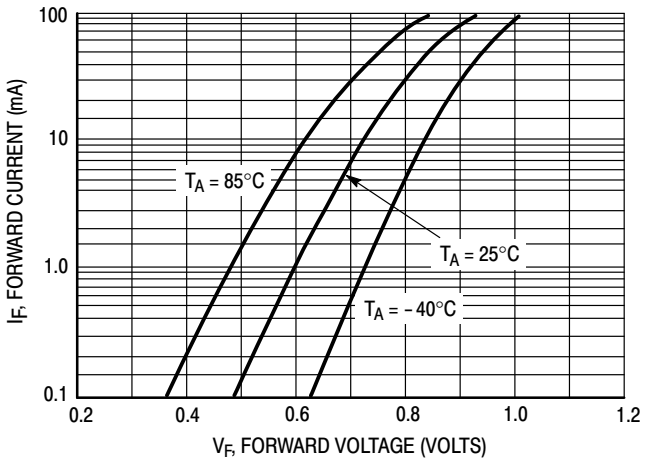


Figure 4. Forward Voltage

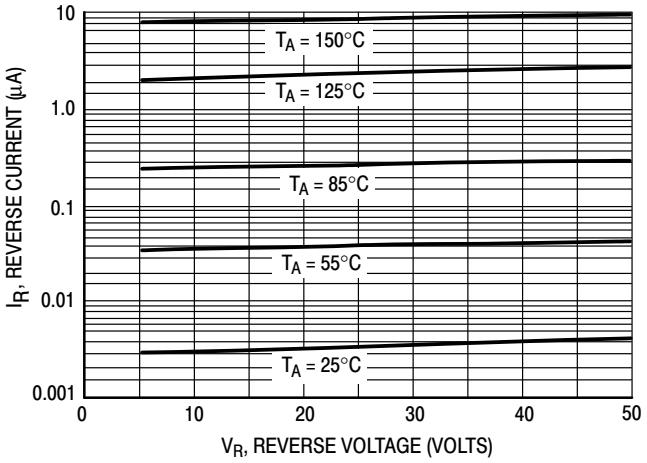


Figure 5. Leakage Current

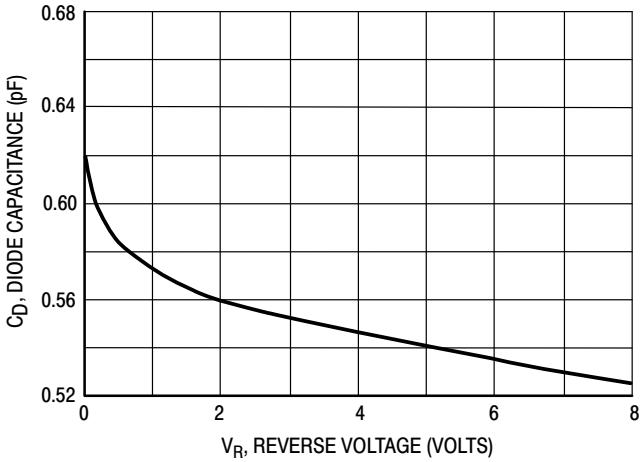
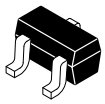


Figure 6. Capacitance

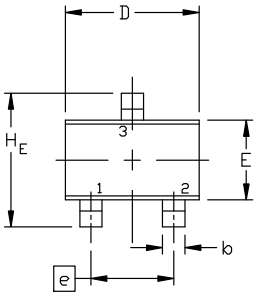
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



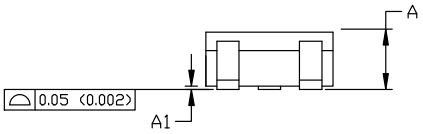
SCALE 4:1

SC−70 (SOT−323)
CASE 419
ISSUE R

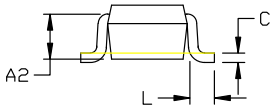
DATE 11 OCT 2022



TOP VIEW



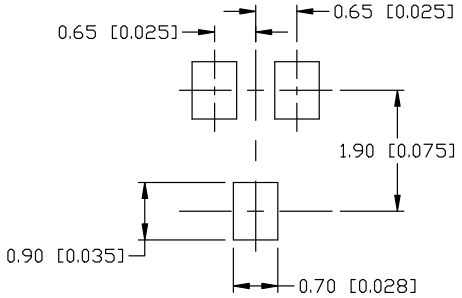
SIDE VIEW



END VIEW

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH

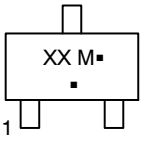
	MILLIMETERS			INCHES		
DIM	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.80	0.90	1.00	0.032	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2	0.70 REF			0.028 BSC		
b	0.30	0.35	0.40	0.012	0.014	0.016
c	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.00	2.20	0.071	0.080	0.087
E	1.15	1.24	1.35	0.045	0.049	0.053
e	1.20	1.30	1.40	0.047	0.051	0.055
e1	0.65 BSC			0.026 BSC		
L	0.20	0.38	0.56	0.008	0.015	0.022
H_E	2.00	2.10	2.40	0.079	0.083	0.095



* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

SOLDERING FOOTPRINT

GENERIC MARKING DIAGRAM



XX = Specific Device Code
M = Date Code
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

STYLE 1:
CANCELLED

STYLE 2:
PIN 1. ANODE
2. N.C.
3. CATHODE

STYLE 3:
PIN 1. BASE
2. EMITTER
3. COLLECTOR

STYLE 4:
PIN 1. CATHODE
2. CATHODE
3. ANODE

STYLE 5:
PIN 1. ANODE
2. ANODE
3. CATHODE

STYLE 6:
PIN 1. EMITTER
2. BASE
3. COLLECTOR

STYLE 7:
PIN 1. BASE
2. EMITTER
3. COLLECTOR

STYLE 8:
PIN 1. GATE
2. SOURCE
3. DRAIN

STYLE 9:
PIN 1. ANODE
2. CATHODE
3. CATHODE−ANODE

STYLE 10:
PIN 1. CATHODE
2. ANODE
3. ANODE−CATHODE

STYLE 11:
PIN 1. CATHODE
2. CATHODE
3. CATHODE

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